

RELIABILITY REPORT
FOR
MAX1820ZEUB
PLASTIC ENCAPSULATED DEVICES

March 21, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Conclusion

The MAX1820 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	V.Quality Assurance Information
II.Manufacturing Information	VI.Reliability Evaluation
III.Packaging Information	
IV.Die InformationAttachments

I. Device Description

A. General

The MAX1820 low-dropout, pulse-width-modulated (PWM) DC-DC buck regulator is optimized to provide power to the power amplifier (PA) in WCDMA cell phones; however, it may be applied in many other applications where high efficiency is a priority. The supply voltage range is from 2.6V to 5.5V, and the guaranteed output current is 600mA; 1MHz PWM switching allows for small external components, while skip mode reduces quiescent current to 180 μ A with light loads.

The MAX1820 is dynamically controlled to provide varying output voltages from 0.4V to 3.4V. The circuit is designed such that the output voltage settles in <30 μ s for a full-scale change in voltage and current.

The MAX1820 includes a low on-resistance internal MOSFET switch and synchronous rectifier to maximize efficiency and minimize external component count; 100% duty-cycle operation allows for low dropout of only 150mV at 600mA load, including the external inductor resistance. The device is offered in 10-pin μ MAX and tiny 3 x 4 chip-scale (UCSP™) packages

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
BATT, OUT (FB), SHDN, SYNC, SKIP, REF to GND	-0.3V to +6.0V
PGND to GND	-0.3V to +0.3V
LX, COMP to GND	-0.3V to (VBATT + 0.3V)
Output Short-Circuit Duration	Infinite
Operating Temperature Range	-40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Ranges	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
10-Pin μ MAX	444mW
Derates above +70°C	
10-Pin μ MAX	5.6mW/°C

II. Manufacturing Information

A. Description/Function:	WCDMA Cellular Phone 600Ma Buck Regulator
B. Process:	S8 - Standard 8 micron silicon gate CMOS
C. Number of Device Transistors:	2722
D. Fabrication Location:	California, USA
E. Assembly Location:	Thailand, Philippines or Malaysia
F. Date of Initial Production:	April, 2001

III. Packaging Information

A. Package Type:	10-Lead μMAX
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-2301-0048
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

IV. Die Information

A. Dimensions:	81 X 81 mils
B. Passivation:	$\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	TiW/ AlCu/ TiWN
D. Backside Metallization:	None
E. Minimum Metal Width:	.8 microns (as drawn)
F. Minimum Metal Spacing:	.8 microns (as drawn)
G. Bondpad Dimensions:	2.7 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Reliability Lab Manager)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 551 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

\triangle Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 1.97 \times 10^{-9} \quad \lambda = 1.97 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The Burn-In Schematic (Spec.# 06-5591) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**) located on the Maxim website at <http://www.maxim-ic.com>.

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The PY72 die type has been found to have all pins able to withstand a transient pulse of $\pm 400\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 250\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX1820ZEUB

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	551	0
Moisture Testing (Note 2)				
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters	77	0

Note 1: Life Test Data may represent plastic D.I.P. qualification lots.

Note 2: Generic process/package data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

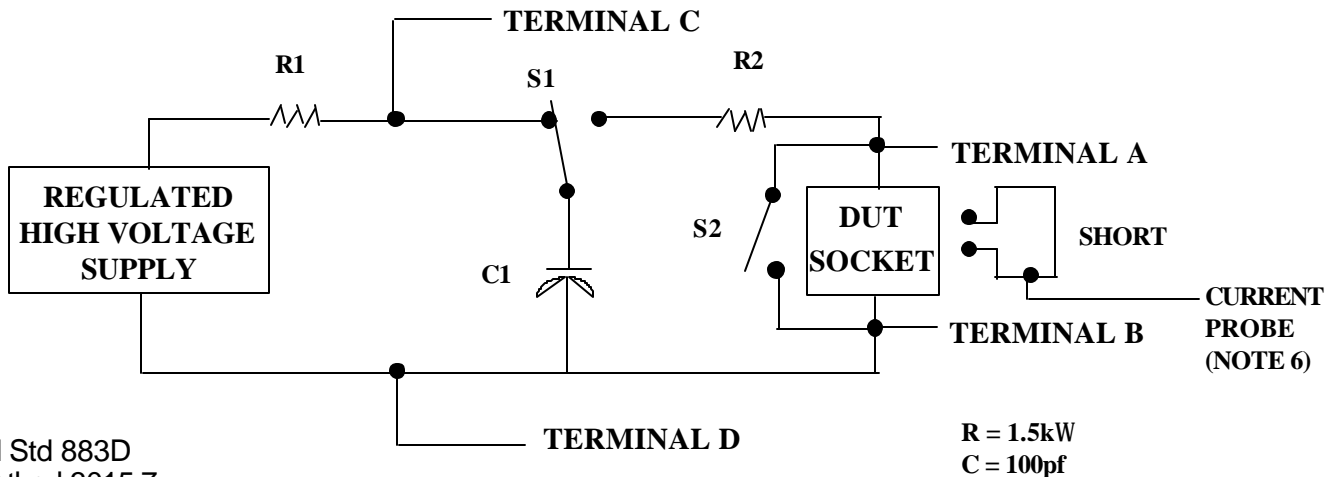
2/ No connects are not to be tested.

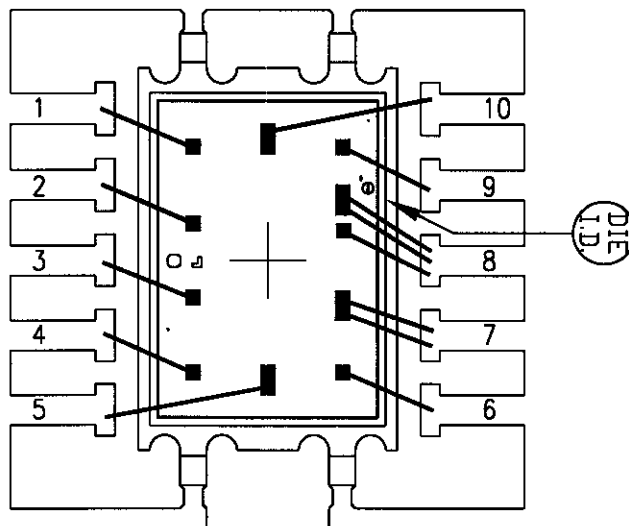
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.

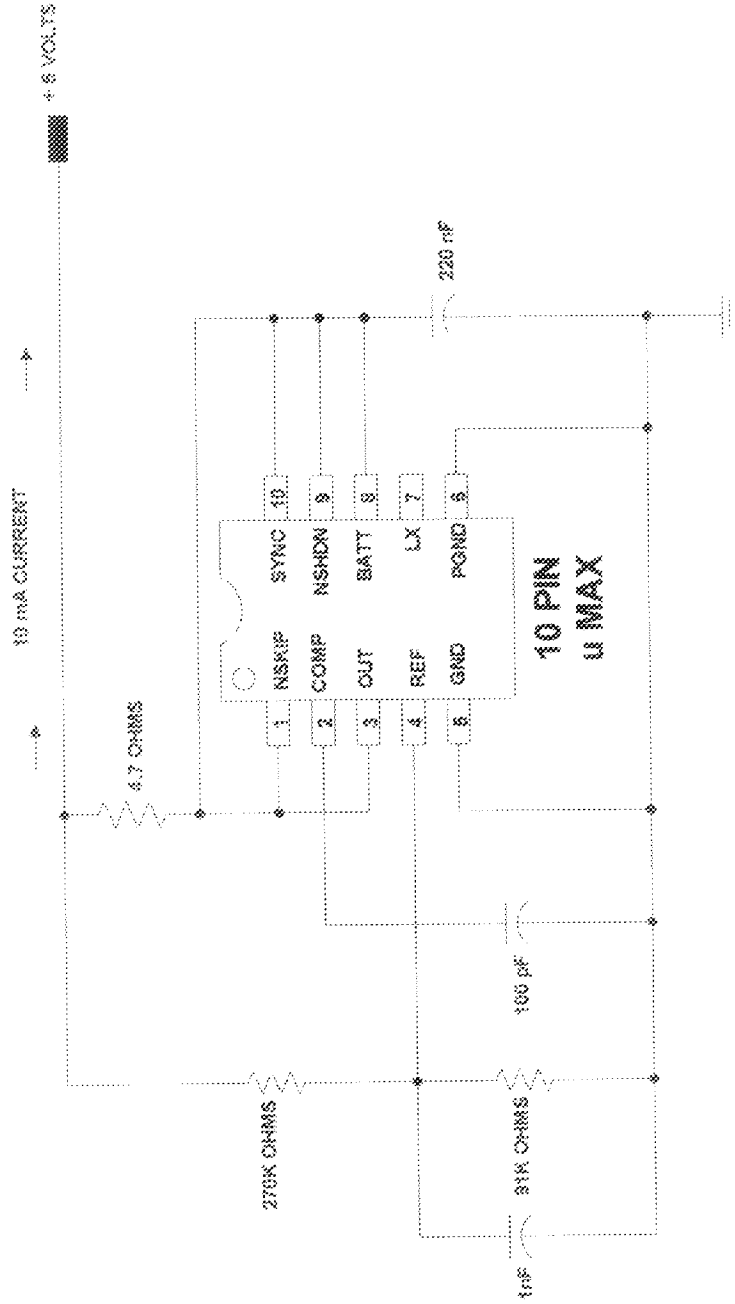




PKG. CODE: U10-2		SIGNATURES	DATE	 CONFIDENTIAL & PROPRIETARY
CAV./PAD SIZE: 68x94	PKG. DESIGN		BOND DIAGRAM #: 05-2301-0048	

ONCE PER SOCKET

ONCE PER BOARD



DRAWN BY:
NOTES:

DEVICES: MAX 1820; MAX 1821

MAXIM BURN-IN SCHEMATIC
SPEC 06-5591 REV. A
DATE: 3 / 8 / 2000

MAX. EXPECTED CURRENT = 10 mA